

TIC216A, TIC216B, TIC216D, TIC216M, TIC216N, TIC216S

SILICON TRIACS

- 6 A RMS
- Glass Passivated Wafer
- 100 V to 800 V Off-State Voltage
- Max I_{GT} of 5 mA (Quadrants 1-3)
- Sensitive gate triacs
- Compliance to ROH

ABSOLUTE MAXIMUM RATINGS

Symbol	Ratings	Value						Unit
			В	D	M	S	N	
V _{DRM}	Repetitive peak off-state voltage (see Note1)	100	200	400	600	700	800	V
I _{T(RMS)}	Full-cycle RMS on-state current at (or below) 70°C case temperature (see note2)	6				Α		
I _{TSM}	Peak on-state surge current full-sine-wave (see Note3)	- I NII			Α			
I _{TSM}	Peak on-state surge current half-sine-wave (see Note4)				Α			
I _{GM}	Peak gate current		± 1					Α
P _{GM}	Peak gate power dissipation at (or below) 85°C case temperature (pulse width ≤200 µs) 2.2				W			
P _{G(AV)}	Average gate power dissipation at (or below) 85°C case (see Note5)				W			
T _C	Operating case temperature range			-40 to +110				°C
T _{stg}	Storage temperature range		-40 to +125					°C
TL	Lead temperature 1.6 mm from case for 10 seconds 230				°C			

THERMAL CHARACTERISTICS

Symbol	Ratings Value		Unit	
R _{∂JC}	Junction to case thermal resistance	≤ 2.5	2.5 °C/W	
R∂JA	Junction to free air thermal resistance	≤ 62.5	C/VV	



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ELECTRICAL CHARACTERISTICS

TC=25°C unless otherwise noted

Symbol	Ratings	Test Condition(s)	Min	Тур	Max	Unit	
I _{DRM}	Repetitive peak off-state current	V_D = Rated V_{DRM} , , I_G = 0 T_C = 110°C	-	-	±2	mA	
I _{GT}	Gate trigger current	V_{supply} = +12 V†, R _L = 10 Ω, $t_{p(g)}$ = > 20 μs	-	-	5		
		V_{supply} = +12 V†, R_L = 10 Ω , $t_{p(g)}$ = > 20 μs	-	-	-5	mA	
		V_{supply} = -12 V†, R _L = 10 Ω , $t_{p(g)}$ = > 20 μs	-	-	-5		
		V_{supply} = -12 V†, R_L = 10 Ω , $t_{p(g)}$ = > 20 μs	-	-	10		
V _{GT}		V_{supply} = +12 V†, R _L = 10 Ω, $t_{p(g)}$ = > 20 μs	-	-	2.2	2 2 V	
	Gate trigger voltage	V_{supply} = +12 V†, R _L = 10 Ω , $t_{p(g)}$ = > 20 μ s	-	-	-2.2		
		V_{supply} = -12 V†, R _L = 10 Ω, $t_{p(g)}$ = > 20 μs	-	-	-2.2		
		V_{supply} = -12 V†, R_L = 10 Ω , $t_{p(g)}$ = > 20 μs	-	-	3		
I _H	Holding current	V_{supply} = +12 V†, I_{G} = 0 initiating I_{TM} = 100 mA	-	-	30	A	
		$V_{\text{supply}} = -12 \text{ V}^{\dagger}, I_G = 0$ initiating $I_{\text{TM}} = -100 \text{ mA}$	-	-	-30	mA	
IL	Latching current	V _{supply} = +12 V† (seeNote7)	-	50	-	mΛ	
		$V_{\text{supply}} = -12 \text{ V} + (\text{seeNote7})$	-	-20	-	mA	
V _{TM}	Peak on-state voltage	$I_{TM} = \pm 8.4 \text{ A}, I_G = 50 \text{ mA (see Note6)}$	-	-	±1.7	V	
dv/dt	Critical rate of rise of off-state voltage	V_{DRM} = Rated V_{DRM} , I_G = 0 T_C = 110°C	-	±50	-	V/ue	
dv/dt _©	Critical rise of communication voltage	V_{DRM} = Rated V_{DRM} , I_{TRM} = ± 8.4A T_{C} = 70°C	±5	-	-	V/µs	

[†] All voltages are whit respect to Main Terminal 1.

Notes:

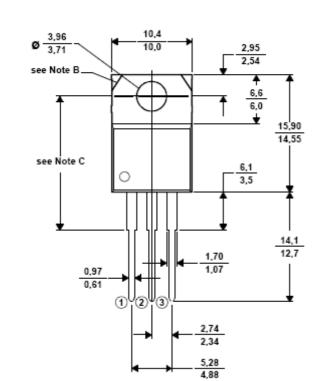
- These values apply bidirectionally for any value of resistance between the gate and Main Terminal
 1.
- 2. This value applies for 50-Hz full-sine-wave operation with resistive load. Above 70°C derate linearly to 110°C case temperature at the rate of 150 mA/°C.
- 3. This value applies for one 50-Hz full-sine-wave when the device is operating at (or below) the rated value of on-state current. Surge may be repeated after the device has returned to original thermal equilibrium. During the surge, gate control may be lost.
- 4. This value applies for one 50-Hz half-sine-wave when the device is operating at (or below) the rated value of on-state current. Surge may be repeated after the device has returned to original thermal equilibrium. During the surge, gate control may be lost.
- 5. This value applies for a maximum averaging time of 20 ms.
- 6. This parameters must be measured using pulse techniques, t_W = ≤1µs, duty cycle ≤ 2 %, voltagesensing contacts, separate from the courrent-carrying contacts are located within 3.2mm (1/8 inch) from de device body.
- 7. The triacs are triggered by a 15-V (open circuit amplitude) pulse supplied by a generator with the following characteristics : $R_G = 100\Omega$, $t_{p(g)} = 20 \mu s$, $t_r = \le 15 ns$, f = 1 kHz.

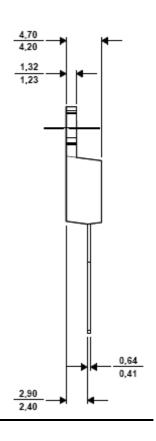


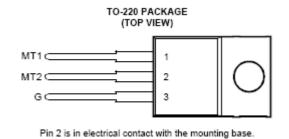
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MECHANICAL DATA CASE TO-220

TO220







Pin 1 :	Main Terminal 1
Pin 2 :	Main Terminal 2
Pin 3 :	Gate

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